

Ming-Hwa Jen

List of Publications by Year in descending order

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14
papers

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1307594

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1281871

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61
citing authors

#	ARTICLE	IF	CITATIONS
1	The mechanical properties and fatigue responses of fiber metal nanocomposite laminates with double-edged cracks. <i>Journal of Mechanics</i> , 2022, 38, 1-12.	1.4	3
2	Fatigue responses of cracked Ti/APC-2 nanocomposite laminates at elevated temperature. <i>Journal of Composite Materials</i> , 2020, 54, 1705-1715.	2.4	1
3	Fabrication and mechanical properties of Ti/APC-2 hybrid nanocomposite laminates at elevated temperatures. <i>Journal of Composite Materials</i> , 2016, 50, 2035-2045.	2.4	9
4	Analysis on the Deflection of Multi-Layered Ceramic Capacitors Due to High Pressure. <i>Mechanics of Advanced Materials and Structures</i> , 2014, 21, 749-760.	2.6	0
5	Prediction and verification strength in APC-2 composite laminates at elevated temperature. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2012, 532, 31-36.	5.6	1
6	Modeling of electromigration on void propagation at the interface between under bump metallization and intermetallic compound in flip-chip ball grid array solder joints. <i>Journal of Applied Physics</i> , 2010, 107, .	2.5	8
7	Electromigration on void formation of Sn3Ag1.5Cu FCBGA solder joints. <i>Microelectronics Reliability</i> , 2009, 49, 734-745.	1.7	18
8	Electromigration Test on Void Formation and Failure Mechanism of FCBGA Lead-Free Solder Joints. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2009, 32, 79-88.	1.3	9
9	Thermo-mechanical fatigue of centrally notched and unnotched AS-4/PEEK APC-2 composite laminates. <i>International Journal of Fatigue</i> , 2006, 28, 901-909.	5.7	19
10	Mechanical Properties in Notched AS-4/PEEK APC-2 Composite Laminates at Elevated Temperature. <i>Journal of Composite Materials</i> , 2006, 40, 955-969.	2.4	11
11	Flip-Chip Ball Grid Array Lead-Free Solder Joint Under Reliability Test. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2005, 127, 446-451.	1.8	9
12	Analysis of a laminated anisotropic plate by Chebyshev collocation method. <i>Composites Part B: Engineering</i> , 2005, 36, 155-169.	12.0	21
13	Analysis of Non-Rectangular Laminated Anisotropic Plates by Chebyshev Collocation Method. <i>JSME International Journal Series A-Solid Mechanics and Material Engineering</i> , 2004, 47, 146-156.	0.4	6
14	Mechanical behavior and fatigue life prediction of fiber metal laminates with inclined edge cracks at elevated temperatures. <i>Mechanics of Advanced Materials and Structures</i> , 0, , 1-10.	2.6	1